

P01000031609

INTERBOND TECHNOLOGIES, INC.  
999 Lexington St. NE  
Palm Bay, Florida 32907

29 March, 2002

200005271512--3  
-04/15/02--01035--002  
\*\*\*\*\*43.75 \*\*\*\*\*43.75

Department of State  
Division of Corporations  
Corporate Filings  
P.O. Box 6327  
Tallahassee, FL 32314

Dear Sir or Madam:

Attached are the articles of dissolution for INTERBOND TECHNOLOGIES, INC.  
Also, enclosed is a check for \$43.75 to cover the cost of filing (\$35.00) and issuance of a  
certified copy of the dissolution (\$8.75).

Thank you for assistance.

Regards,

*Edmond D. Jones*

Edmond D. Jones  
President  
Interbond Technologies  
Enclosure (2)

Cc: The Company Corporation

FILED  
02 APR 15 AM 11:22  
CLERK OF STATE  
TALLAHASSEE, FLORIDA

13  
4/17/02  
Diss

## ARTICLES OF DISSOLUTION

**FILED**

02 APR 15 AM 11:22

SECRETARY OF STATE  
TALLAHASSEE, FLORIDA

Pursuant to 607.1401, Florida Statutes, this Florida profit corporation submits the following articles of dissolution.

FIRST: The name of the corporation is INTERBOND TECHNOLOGIES, INC.

SECOND: The filing date of the articles of incorporation was March 28<sup>th</sup>, 2001

THIRD: The business opportunity originally pursued did not materialize. As a result, the corporation has not commenced business.


FOURTH: No debt of the corporation remains unpaid.

FIFTH: The net assets of the corporation remaining after winding have been distributed to the shareholders, if shares were issued.

SIXTH: Adoption of Dissolution;

A majority of the incorporators authorized the dissolution.

Signed this 17<sup>th</sup> day of January 2002.



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Edmond D. Jones  
President, Interbond Technologies, Inc.